

1612507-3 ✓ ACTIVE

DDR SODIMM, DDR2 SO DIMM

TE Internal #: 1612507-3

DDR SODIMM, SO DIMM Sockets, Double Data Rate (DDR), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, Surface Mount, Cable-to-Board

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR2 SO DIMM Sockets



DRAM Type: **Double Data Rate (DDR)**

Stack Height: **5.2 mm [.205 in]**

Module Orientation: **Right Angle**

PCB Mounting Style: **Surface Mount**

Connector System: **Cable-to-Board**

[All DDR2 SO DIMM Sockets \(30\)](#)

Features

Product Type Features

DRAM Type	Double Data Rate (DDR)
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket

Configuration Features

Number of Bays	2
Center Key	None
Number of Keys	1
Module Orientation	Right Angle
Number of Positions	200
Number of Rows	2
Keying	Standard



Electrical Characteristics

DRAM Voltage	2.5 V
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Signal Characteristics

SGRAM Voltage	2.5 V
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Body Features

Retention Post Material	Copper Alloy
Ejector Location	Both Ends
Latch Material	Stainless Steel
Latch Plating Material	Tin
Module Key Type	SGRAM
Ejector Type	Locking
Connector Profile	Standard

Contact Features

Socket Style	SO DIMM
PCB Contact Termination Area Plating Material	Gold Flash
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold Flash
Contact Current Rating (Max)	.5 A
Socket Type	Memory Card

Termination Features

Insertion Style	Cam-In
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Mechanical Attachment

PCB Mount Retention	With
PCB Mount Retention Type	Solder Tail
PCB Mounting Style	Surface Mount
Connector Mounting Type	Board Mount

Housing Features

Centerline (Pitch)	.6 mm [.024 in]
Housing Color	Black
Housing Material	High Temperature Thermoplastic

Dimensions



Stack Height	5.2 mm[.205 in]
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Row-to-Row Spacing	6.2 mm[.244 in]
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Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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Operation/Application

Circuit Application	Power
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Method	Hard Tray
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Packaging Quantity	16
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Other

Comment	Solder peg plating, tin.
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC
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Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
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Solder Process Capability	Reflow solder capable to 245°C
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Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on




requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts




TE Part # CAT-D33047-SO1339
DDR4 SO DIMM SOCKETS

Also in the Series | DDR SODIMM



SO DIMM Sockets(7)

Also in the Series | DDR2 SO DIMM



SO DIMM Sockets(24)

Customers Also Bought



TE Part #1658643-1
D-Sub Crimp Recept Signal 9 Posn, Socket Size 20, Shell Size 1



TE Part #1-87631-2
16 MODIV HSG DR MRKD .100 POL



TE Part #1-87631-6
20 MODIV HSG DR MRKD .100 POL



TE Part #1565357-1
ON TAPING(EMBOSS)0.5MM PITCH B



Documents

Product Drawings

HARD TRAY ASS'Y DDR SODIMM SOC

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_1612507-3_D1.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1612507-3_D1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1612507-3_D1.3d_stp.zip](#)

English

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Product Specifications

Application Specification

English

Product Environmental Compliance

TE Material Declaration

English